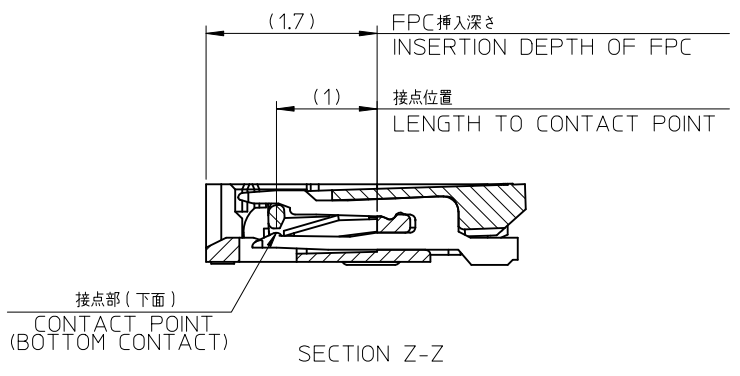


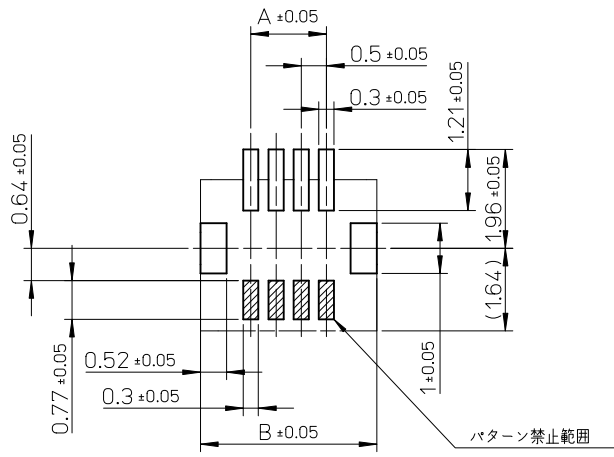
注記
NOTES:

- 1.材質
MATERIAL
ハウジング:耐熱性樹脂、ガラス充填、UL94HB、難燃剤使用
HOUSING:HEAT RESISTANCE POLYMER, GLASS FILLED, UL94HB
FLAME RETARDANTS FREE
アクチュエータ:耐熱性樹脂、ガラス充填、UL94HB、難燃剤使用
ACTUATOR:HEAT RESISTANCE POLYMER, GLASS FILLED, UL94HB
FLAME RETARDANTS FREE
ターミナル:銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
補強金具:銅合金 (t=0.15)
NAIL: COPPER ALLOY (t=0.15)
- 2.めっき仕様
PLATING
ターミナル: 部分金メッキ
接点部 0.1マイクロメートル以上
半田付け部 0.05マイクロメートル以上
TERMINAL: SEPARATED GOLD PLATING
CONTACT AREA 0.1 MICROMETER MINIMUM.
SOLDER TAIL AREA 0.05 MICROMETER MINIMUM.
下地 ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING; NICKEL PLATING 1.0 MICROMETER MINIMUM.
補強金具: 錫メッキ 1.0マイクロメートル以上
NAIL: TIN PLATING 1.0 MICROMETER MINIMUM.
下地 ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING; NICKEL PLATING 1.0 MICROMETER MINIMUM.
- 3.平坦度は、0.1mm以下とする。
TAILS AND NAILS COPLANARITY TO BE 0.1mm MAXIMUM.
- 4.ELV AND RoHS COMPLIANT.

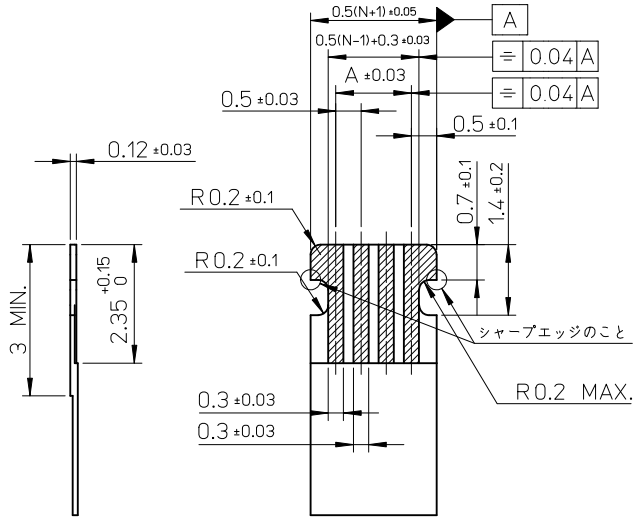


| | | | | | | | |
|-----|------|------|-----|-----|-------------------------------|----------------------|----------------------|
| 4.5 | 4.97 | 4.18 | 5.5 | 3.5 | 501461-0812 | 501461-0818 | 8 |
| E | D | C | B | A | エンボス梱包品 EMBOSSED PACKAGING | 製品番号 MATERIAL NO. | 極数(N) CIRCUITS(N) |

| | | | | | | | |
|---|---------------------------------------|-------------|--|--|--|------------------------|------------------------|
| RELEASED EC NO: J2011-0733 DRWN: AISHI 2010/11/29 CHKD: TAKAHASHI 2010/11/29 APPR: KMORIKAWA 2010/12/01 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE 10:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| | 10 UNDER | ±0.2 | DRAWN BY AISHI | | TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY | | |
| | 10 OVER 30 UNDER | ±0.25 | CHECKED BY TAKAHASHI | | MOLEX INCORPORATED | | |
| | 30 OVER | ±0.3 | APPROVED BY KMORIKAWA | | DOCUMENT NO. SD-501461-007 | | |
| A | REV | ANGULAR ±1° | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | SEE TABLE | | SHEET NO. 1 OF 2 |
| | | | | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | |



推奨基板寸法
RECOMMENDED P.C.BOARD PATTERN LAYOUT

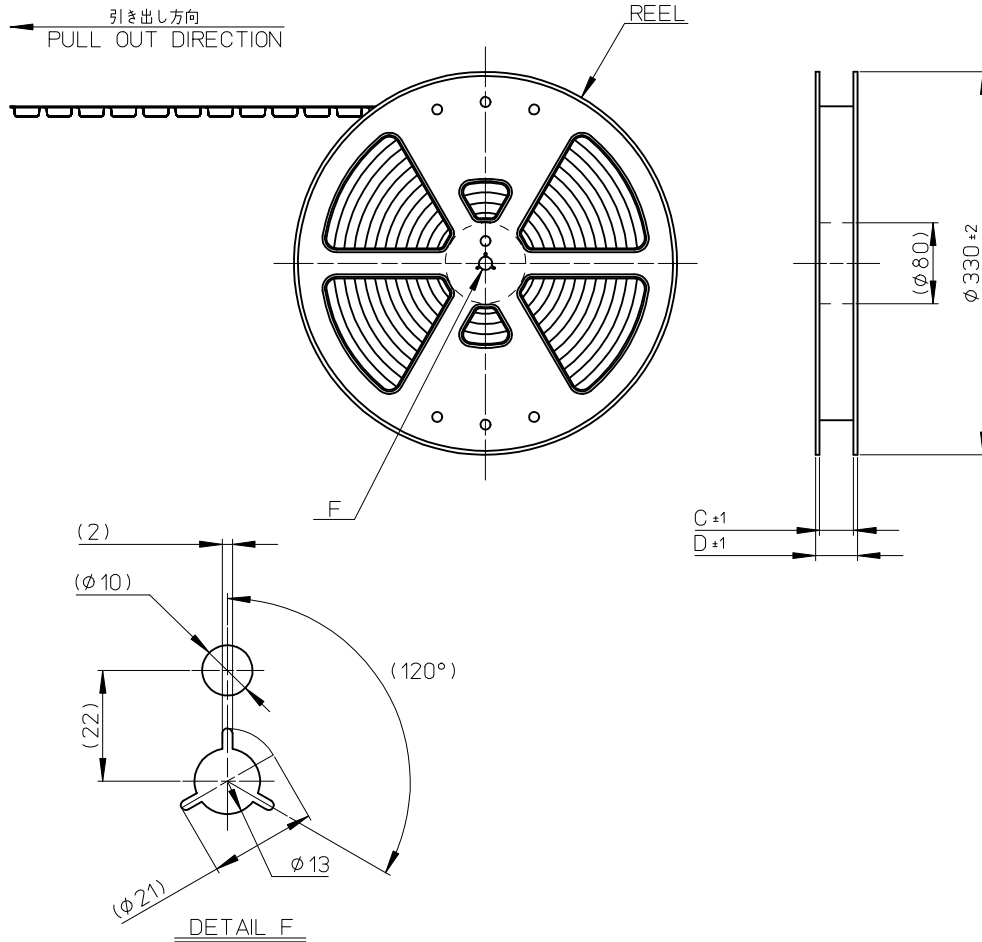


推奨FPC寸法
RECOMMENDED FPC PATTERN LAYOUT

FPCについて：
 抜き方向は、導体側から補強板側を推奨します。
 補強フィルム材質は、ポリイミドを推奨します。
 接着剤は、熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は、導通不良の原因となりますので染み出しが無いよう、お願いします。

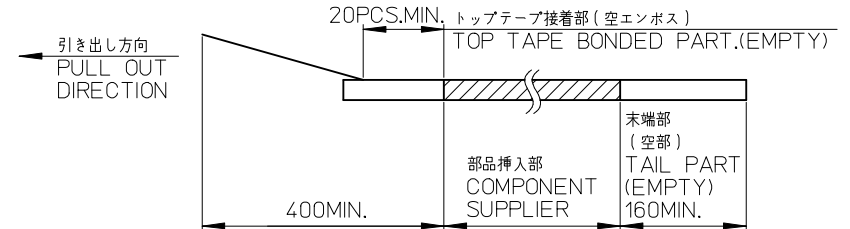
ABOUT FPC:
 RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFNER FILME SIDE.
 RECOMMENDED MATERIAL:
 STIFFNER FILME: POLYIMIDE
 BONDING AGENT: THRMOSSETTING AGENT
 PLEASE PUT APPROPRIATE AMOUNT OF ASHESIVE MAY CAUSE
 THE DEFECT IN ELECTRICAL CONTINUITY.

| | | | | | | | | |
|---|---------------------------------------|------------|---|--------------------|--|------------------------|------------------------|--|
| RELEASED EC NO: J2011-0733 DRW: AISHII 2010/11/29 CHK: KTAKAHASHI 2010/11/29 APPR: KMORIKAWA 2010/12/01 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE 10:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | |
| | 10 UNDER | ±0.2 | DRAWN BY AISHII | DATE 2010/11/29 | TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY | | | |
| | 10 OVER 30 UNDER | ±0.25 | CHECKED BY KTAKAHASHI | DATE 2010/11/29 | MOLEX INCORPORATED | | | |
| | 30 OVER | ±0.3 | APPROVED BY KMORIKAWA | DATE 2010/12/01 | | | | |
| | ANGULAR | ±1 ° | MATERIAL NO. SEE SHEET 1 | | DOCUMENT NO. SD-501461-007 | SHEET NO. 2 OF 2 | | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | SIZE A3 | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | |



NOTES

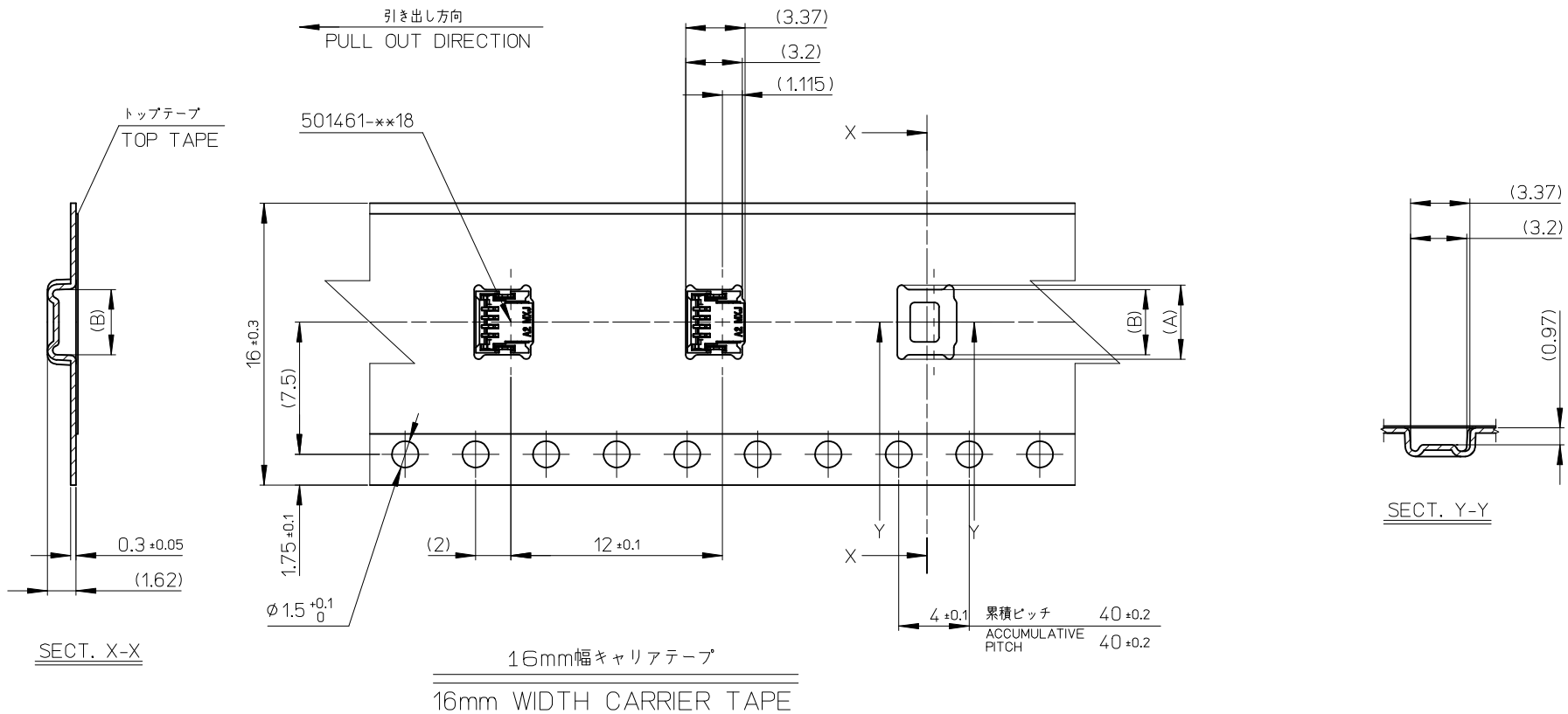
- 製品詳細寸法については製品単体図面を参照下さい。
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量: 3000個/リール
NUMBER OF CONNECTORS 3000PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- 材料
MATERIAL
キャリアテープ(CARRIRE TAPE): ポリスチレン (POLYSTYRENE)
トップテープ(TOP TAPE): PET, PE, PEF
リール(REEL): ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAILED>
- ELV 及び RoHS 適合品.
ELV AND RoHS COMPLIANT.

| | | | | | | | | | |
|---|--------------------|--|--|--|--|-------------------------------|--|-----------|--|
| REVISED EC NO: J2013-1055 DRWN: SANUMA 2013/03/26 CHKD: TAKAHASHI 2013/03/26 APPR: KMORIKAWA 2013/04/03 | DESCRIPTION REV | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE --- | 501461-**12 | MODEL NO. | |
| | | 10 UNDER ± 0.2 | | DRAWN BY DATE AISHII 2010/11/29 | | TITLE | 0.5 FPC CONN BACK FLIP H=0.8 EMBSTP PKG | | |
| | | 10 OVER 30 UNDER ± 0.25 | | CHECKED BY DATE KTAKAHASHI 2010/11/29 | | | | | |
| | | 30 OVER ± 0.3 | | APPROVED BY DATE KMORIKAWA 2010/12/01 | | | | | |
| ANGULAR ± 1 ° | | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | MATERIAL NO. SEE SHEET 2 | | DOCUMENT NO. SD-501461-008 | SHEET NO. 1 OF 2 | | |
| SIZE A3 | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | | | |

10 9 8 7 6 5 4 3 2 1



| | | | | | | |
|--------------------------------|------|------|-----|-----|--------------|----------------|
| 16 | 21.4 | 17.4 | 5.7 | 6.2 | 501461-0812 | 8 |
| キャリアテープ幅 CARRIER TAPE WIDTH | D | C | (B) | (A) | MATERIAL NO. | 極数 CIRCUITS |

| | | | | | | | | |
|--|---|--------------------------|-----------------------------------|--|-------------------------------|-------------------------------|--------------------------|---------------------------|
| SEE SHEET 1 EC NO: J2013-1055 DRWN:NASUNUMA 2013/03/26 CHKD:KTAKAHASHI 2013/03/26 APPR:KMORIKAWA 2013/04/03 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE --- | DESIGN UNITS METRIC | MODEL NO. 501461-**12 | THIRD ANGLE PROJECTION |
| | 10 UNDER ± 0.2 10 OVER 30 UNDER ± 0.25 30 OVER ± 0.3 | DRAWN BY AISHII | DATE 2010/11/29 | TITLE 0.5 FPC CONN BACK FLIP H=0.8 EMBSTP PKG | | | | |
| | ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | CHECKED BY KTAKAHASHI | DATE 2010/11/29 | molex | | | | |
| | SEE TABLE | APPROVED BY KMORIKAWA | DATE 2010/12/01 | MATERIAL NO. SEE TABLE | DOCUMENT NO. SD-501461-008 | SHEET NO. 2 OF 2 | | |

9 8 7 6 5 4 3 2